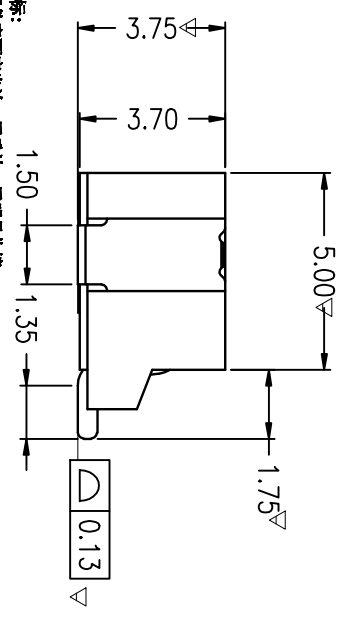
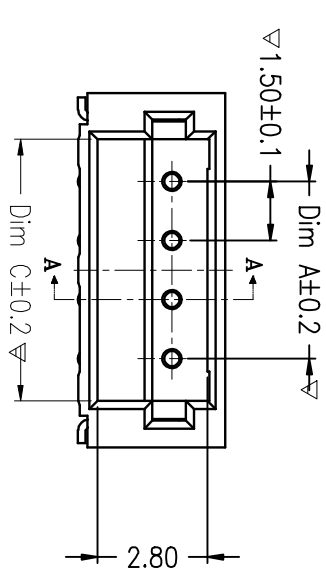
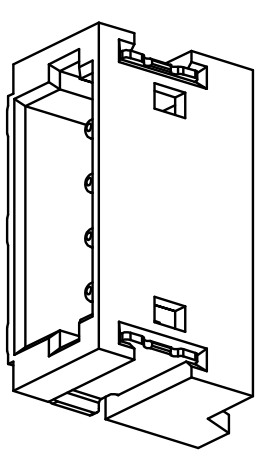
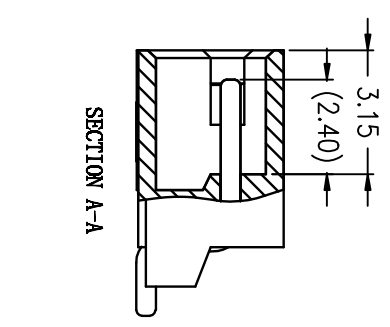
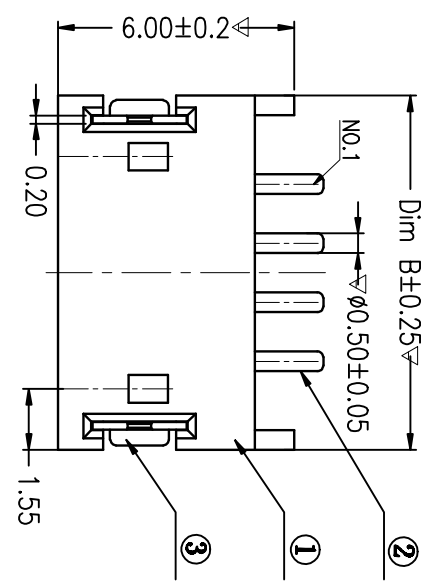
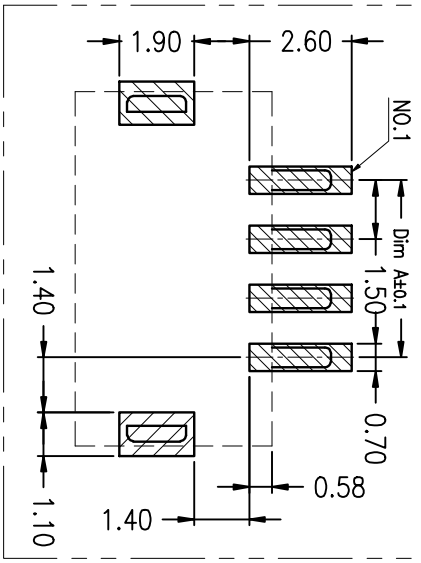


REV(版本)	DESCRIPTION(描述)	NAME(名字)	DATE(日期)



CKT	Dim A	Dim B	Dim C
2	1.50	6.00	3.65
3	3.00	7.50	5.15
4	4.50	9.00	6.65
5	6.00	10.50	8.15
6	7.50	12.50	9.65
7	9.00	13.50	11.15
8	10.50	15.50	12.65
9	12.50	16.50	14.15
10	13.50	18.50	15.65
11	15.50	19.50	17.15
12	16.50	21.50	18.65
13	18.50	22.50	20.15
14	19.50	24.50	21.65
15	21.50	25.50	23.15
16	22.50	27.50	24.65
17	24.50	28.50	26.15
18	25.50	30.00	27.65
19	27.50	31.50	29.15
20	28.50	33.00	30.65

通用线路板



技术指标:

1. 塑件表面应光洁、无毛边、无明显收缩、缺角、翘纹等现象。
2. 温度范围: -25° C~85° C, Working temp:-25° C~85° C.
3. 额定电压: 100V, AC/DC. Voltage rating:100V AC/DC(rms)
4. 接触电阻: ≤40m Ω. Contact resistance:40m Ω max.
5. 绝缘电阻: ≥900M Ω. Insulation resistance:900M Ω min
6. 额定电流: 1A, AC/DC. Current rating:1A AC/DC
7. 耐电压: AC 500V/1分钟. Withstanding Voltage:500V AC/minute
8. PIV保持力: 10N min. pin Retention Force:10N min
9. 主体材料: LCP UL94-V0, 本色. Housing material:LCP UL94-V0, 本色
10. 端子材: 黄铜C2680, 镀镍50μ min, 镀亮锡100μ min. Terminal material: Brass C2680, plating Ni 50μ min, plating Tin 100μ min
11. 铜片材料: 黄铜C2680, 镀镍50μ min, 镀亮锡100μ min. Solder tab material: Brass C2680, plating Ni 50μ min, plating Tin 100μ min
12. 符号“∇”为重点管控 MAJOR DIMENSION: ∇

一般公差 (TOLERANCE)		
X ±0.50	XX ±1.0	
ANGLES ±1°		

深圳市连欣科技有限公司

品名 (TITLE)	料号 (PART NO)	制图 (DWG)	审核 (APPV)
Pitch:1.50mm ZH 领域 SMT	XDWF-0151WT-***P	XL10	Alex
比例 (SCALE)	1:1	页码 (SHEET)	1 OF 1
单位 (UNITS)	MM	尺寸 (SIZE)	A4
		版本 (REV)	A